

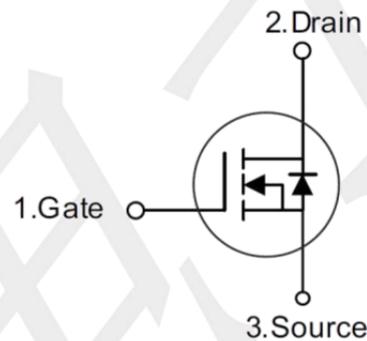
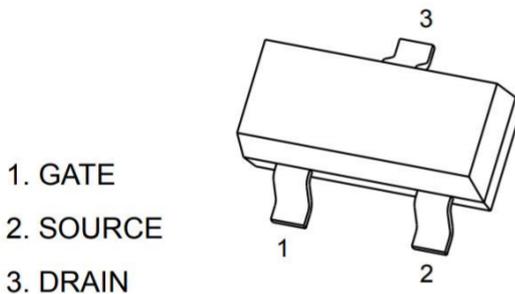
Product Summary

- V_{DS} 200 V
- I_{DS} ($V_{GS}=10V$) 1.0 A
- $R_{DS(ON)}$ ($V_{GS}=10V$) $\leq 1.7\Omega$ (Typ)

Application

- Interfacing Switching
- DC-DC Converters
- Power management functions

Package and Pin Configuration



SOT23

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

| PARAMETER | SYMBOL | LIMIT | UNIT |
|---|-----------|------------------------|------------------|
| Drain-Source Voltage | V_{DS} | 200 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current $T_A=25^\circ\text{C}$ | I_D | 1.0 | A |
| Continuous Drain Current $T_A=70^\circ\text{C}$ | I_D | 0.7 | A |
| Pulsed Drain Current ($t = 100 \mu\text{s}$) | I_{DM} | 4.0 | A |
| Maximum Power Dissipation | P_D | $T_A=25^\circ\text{C}$ | 1.0 |
| | | $T_A=70^\circ\text{C}$ | 0.8 |
| Operating Junction Temperature Range | T_J | -55 to +150 | $^\circ\text{C}$ |
| Storage Temperature Range | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

Thermal Characteristic

| PARAMETER | Symbol | Value | Unit |
|--|-----------------|-------|--------------------|
| Thermal Resistance from Junction to Ambient($t \leq 10\text{s}$) | $R_{\theta JA}$ | 125 | $^\circ\text{C/W}$ |

Note : When mounted on 1" square PCB (FR4 material).

Electrical Characteristics (T_A=25°C unless otherwise noted)

| PARAMETER | CONDITIONS | SYMBOL | MIN | TYP | MAX | UNIT |
|--|---|---------------------|-----|-----|------|------|
| Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | V _{GS} =0V, I _D = 250μA | BV _{DSS} | 200 | -- | -- | V |
| Gate-Source Threshold Voltage | V _{DS} =V _{GS} , I _D = 250μA | V _{GS(th)} | 1.0 | 1.7 | 2.0 | V |
| Gate-Source Leakage | V _{DS} =0V, V _{GS} = ±20V | I _{GSS} | -- | -- | ±100 | nA |
| Zero Gate Voltage Drain Current | V _{DS} = 200V, V _{GS} =0V | I _{DSS} | -- | -- | 1.0 | μA |
| Drain-Source On-State Resistance (Note 1) | V _{GS} = 10V, I _D =0.8A | R _{DS(on)} | -- | 1.7 | 2.0 | Ω |
| | V _{GS} = 5V, I _D = 0.5A | | -- | 1.9 | 2.4 | |
| Forward Transconductance (Note 2) | V _{DS} = 2V, I _D =1A | g _{fs} | -- | 5 | -- | S |
| Dynamic (Note 2) | | | | | | |
| Input Capacitance | V _{DS} = 25V, V _{GS} = 0V, F = 1.0MHz | C _{iss} | -- | 150 | -- | pF |
| Output Capacitance | | C _{oss} | -- | 85 | -- | |
| Reverse Transfer Capacitance | | C _{rss} | -- | 3.0 | -- | |
| Switching | | | | | | |
| Turn-On Delay Time (Note 3) | V _{DS} = 100V, V _{GS} = 10V, I _D = 1.0A, R _G = 1Ω. | t _{d(on)} | -- | 9.0 | -- | nS |
| Rise Time (Note 3) | | t _r | -- | 12 | -- | |
| Turn-Off Delay Time (Note 3) | | t _{d(off)} | -- | 14 | -- | |
| Fall Time (Note 3) | | t _f | -- | 13 | -- | |
| Total Gate Charge | V _{DS} = 100V, I _D = 1A, V _{GS} = 10V | Q _g | -- | 5.6 | -- | nC |
| Gate Source Charge | | Q _{gs} | -- | 0.8 | -- | |
| Gate Drain Charge | | Q _{gd} | -- | 1.9 | -- | |
| Source-Drain Diode Ratings and Characteristics (Note 2) | | | | | | |
| Forward Voltage | V _{GS} = 0V, I _F = 0.1A | V _{SD} | -- | 0.8 | 1.2 | V |
| Continuous Source Current | Integral reverse diode in the MOSFET | I _S | -- | -- | 1.0 | A |
| Pulsed Current (Note 1) | | I _{SM} | -- | -- | 4.0 | A |

Notes:

1. Pulse test; pulse width ≤ 300 μS, duty cycle ≤ 2%.
2. Guaranteed by design, not subject to production testing.
3. Independent of operating temperature

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Figure 1. Output Characteristics

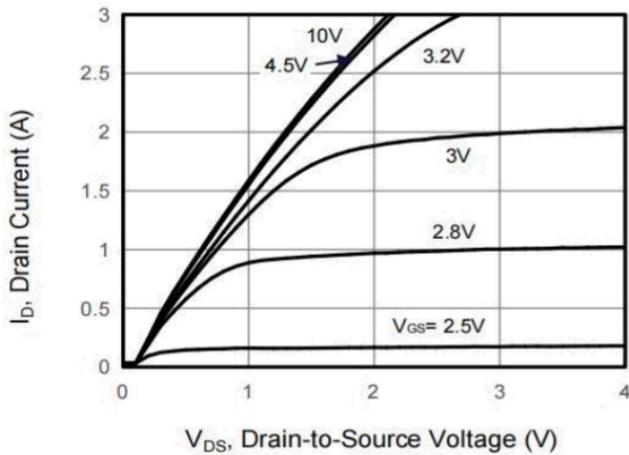


Figure 2. Transfer Characteristics

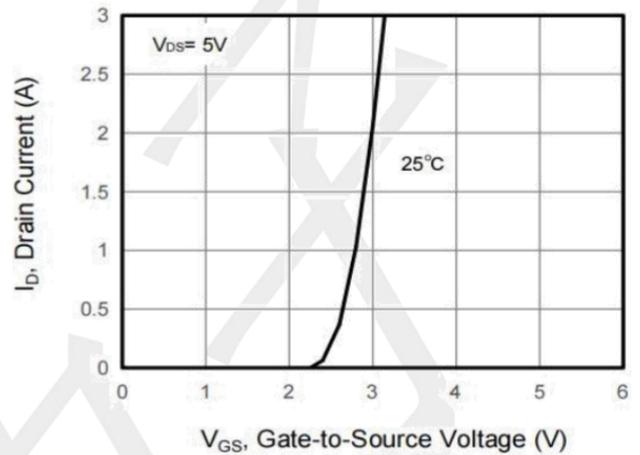


Figure 3. Drain Source On Resistance

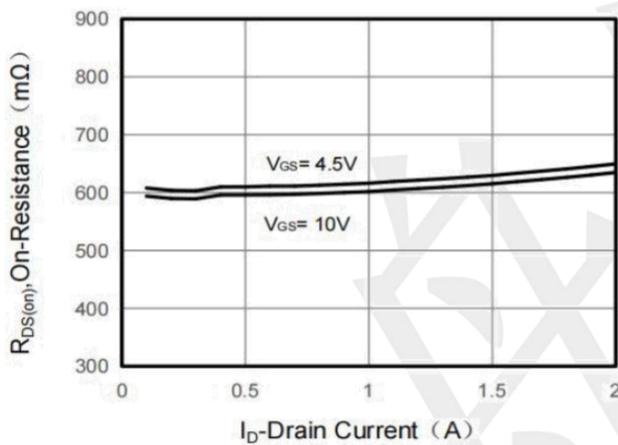


Figure 4. Gate Charge

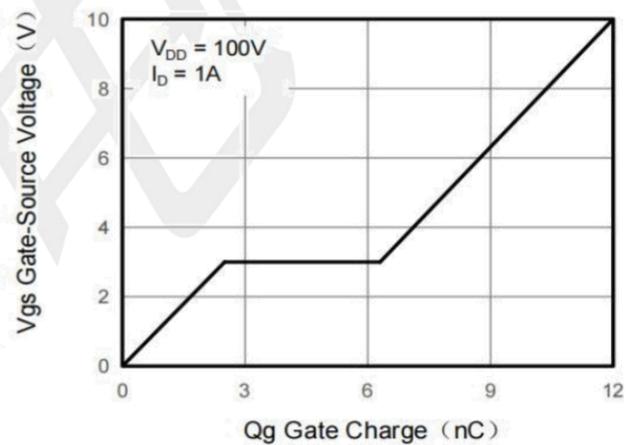


Figure 5. Capacitance

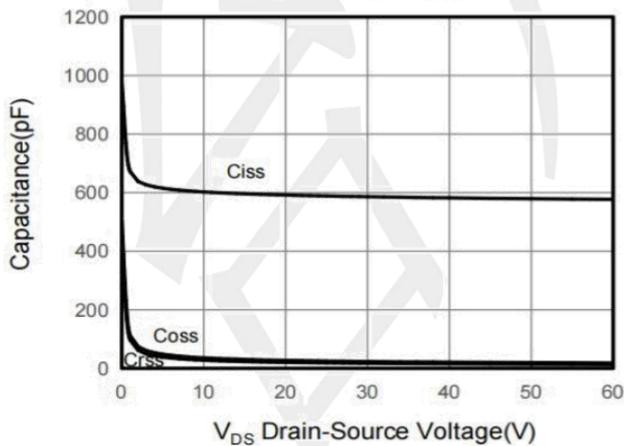
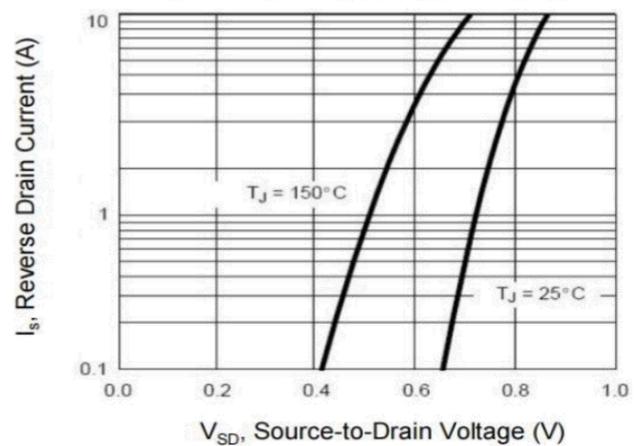
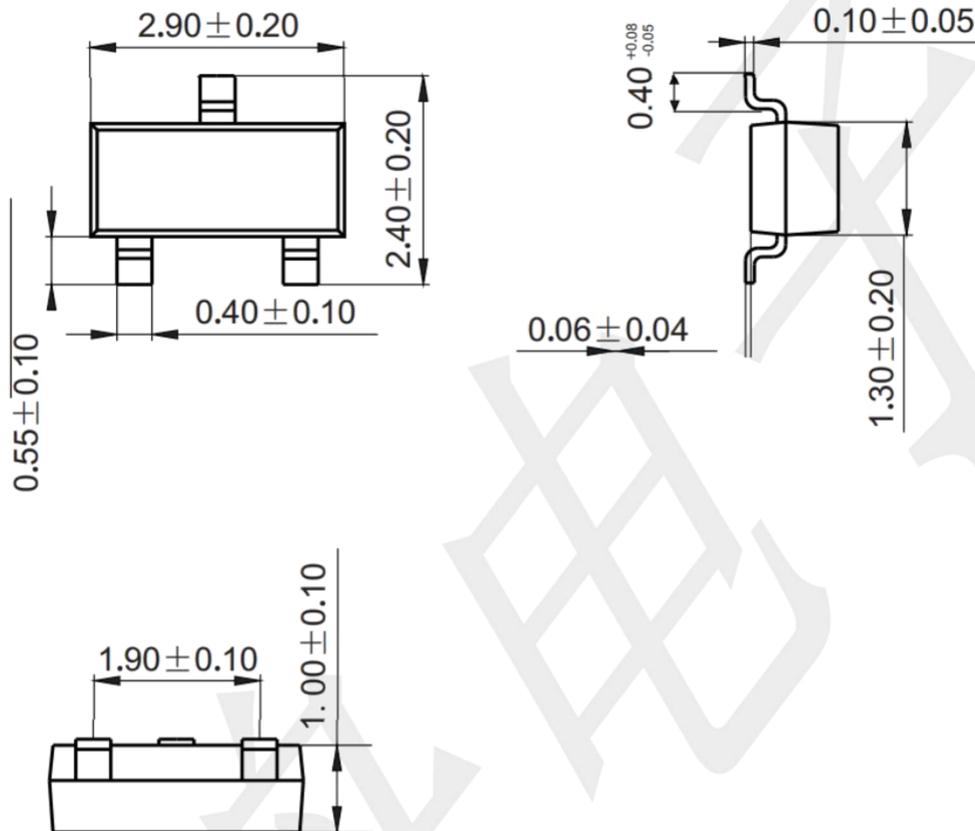


Figure 6. Source-Drain Diode Forward



Package Outline Dimensions (unit: mm)

SOT23



Mounting Pad Layout (unit: mm)

